REMARKS/ARGUMENTS

Favorable reconsideration of this application in view of the following remarks is respectfully requested.

Claims 7-12 are presently active in this case. Claim 7 has been amended by way of the present amendment.

In the outstanding office action, claim 7 was objected to for being unclear; claims 7-11 were rejected under 35 USC 102(b) as being anticipated by U.S. patent No. 5,691,793 to Watanabe et al.; and claim 12 was rejected under 35 USC 103(a) as being unpatentable over Watanabe et al. in view of U.S. patent No. 6,317,173 to Jung et al.

In response to the objection to claim 7, claim 7 has been amended to clarify (a) that the array substrate has an upper side and a lower side and (b) that the first wiring layer is formed on a layer closer to the lower side of the array substrate than the second wiring layer and the second wiring layer is formed on a layer closer to the upper side of the array substrate than the first wiring layer. See Figure 11 and the corresponding disclosure at page 12 lines 19-28 for a non-limiting example. No new matter has been added.

Briefly recapitulating, the present invention (illustrated by way of the non-limiting example of Fig. 11) provides first wiring layer 73 connected to an auxiliary capacity electrodes 66, a second wiring layer 74 connected to a switching element 68 and the first wiring layer 73, and a third wiring layer 76 connected to an upper electrode 75 connected to the pixel electrode and the switching element 68. As discussed above, the first wiring layer 73 is formed on a layer closer to the lower side of the array substrate 100 than the second wiring layer 74 and the second wiring layer 74 is formed on a layer closer to the upper side of the array substrate 100 than the first wiring layer 73.

This configuration enables a short-circuit defect between the auxiliary capacity electrode and an auxiliary capacity feeder to be corrected prior to forming a cell by

irradiating a laser beam on the upper side of the array substrate in order to cut the second wiring layer. If a short circuit is detected after formation of the cell, a laser can be applied to the lower side of the array substrate to cut the first wiring layer. See page 12 lines 19-28 of the Specification.

The official action asserts on page 3 line 1 that conductive pattern 421 of Watanabe et al. corresponds to the first wiring pattern defined by claim 7. However, the official action concedes that it is interpreting claim 7 to "mean that the layers are formed in a vertical manner relative to each other." In light of the amendment to claim 7 clarifying the relationship between the first and second wiring layers, applicants respectfully submit that Watanabe et al. fail to disclose or suggest the invention defined by claim 7 as it fails to teach or suggest that the conductive pattern 421 is formed on a layer closer to the lower side of an array substrate than a second wiring layer and that the second wiring layer is formed on a layer closer to the upper side of the array substrate than the conductive pattern 421.

Consequently, the device disclosed by Watanabe et al. cannot enable a short-circuit defect between an auxiliary capacity electrode and an auxiliary capacity feeder to be corrected prior to forming a cell by irradiating a laser beam on the upper side of an array substrate in order to cut a second wiring layer. Furthermore, in the event of a short circuit being detected after formation of the cell, Watanabe et al. do not enable a laser to be applied to the lower side of the array substrate to cut a first wiring layer.

Applicants submit that Jung et al. (U.S. Patent No. 6,317,173) does not remedy the deficiencies of Watanabe et al. Consequently, Watanabe et al. are not believed to anticipate or render obvious the subject matter defined by claim 7 when considered alone or in combination with Jung et al. Claims 8-12 are believed to be allowable for at least the same reasons that claim 7 is believed to be allowable.

Applicants hereby request a personal interview with the examiner regarding the outstanding issues.

Consequently, no other issues are believed to be outstanding and hence the application is believed to be in condition for allowance. An early and favorable action is respectfully requested.

Respectfully submitted,

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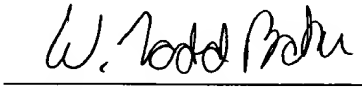
MAIER & NEUSTADT, P.C.



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